



Material Content Data Sheet



Sales Product Name		IGW25T120		Issued		29. August 2013			
MA#		MA000923534							
Package		PG-TO247-3-41		Weight*		6048.73 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.851	0.15	0.15	1463	1463	
leadframe	non noble metal	iron	7439-89-6	3.972	0.07		657		
	inorganic material	phosphorus	7723-14-0	1.192	0.02		197		
	non noble metal	copper	7440-50-8	3967.074	65.58	65.67	655853	656707	
wire	non noble metal	aluminium	7429-90-5	4.355	0.07	0.07	720	720	
encapsulation	organic material	carbon black	1333-86-4	19.976	0.33		3303		
	plastics	epoxy resin	-	379.553	6.27		62749		
	inorganic material	silicondioxide	60676-86-0	1598.119	26.42	33.02	264207	330259	
leadfinish	non noble metal	tin	7440-31-5	31.874	0.53	0.53	5270	5270	
plating	non noble metal	nickel	7440-02-0	29.065	0.48	0.48	4805	4805	
solder	non noble metal	antimony	7440-36-0	0.469	0.01		78		
	noble metal	silver	7440-22-4	1.173	0.02		194		
	non noble metal	tin	7440-31-5	3.051	0.05	0.08	504	776	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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